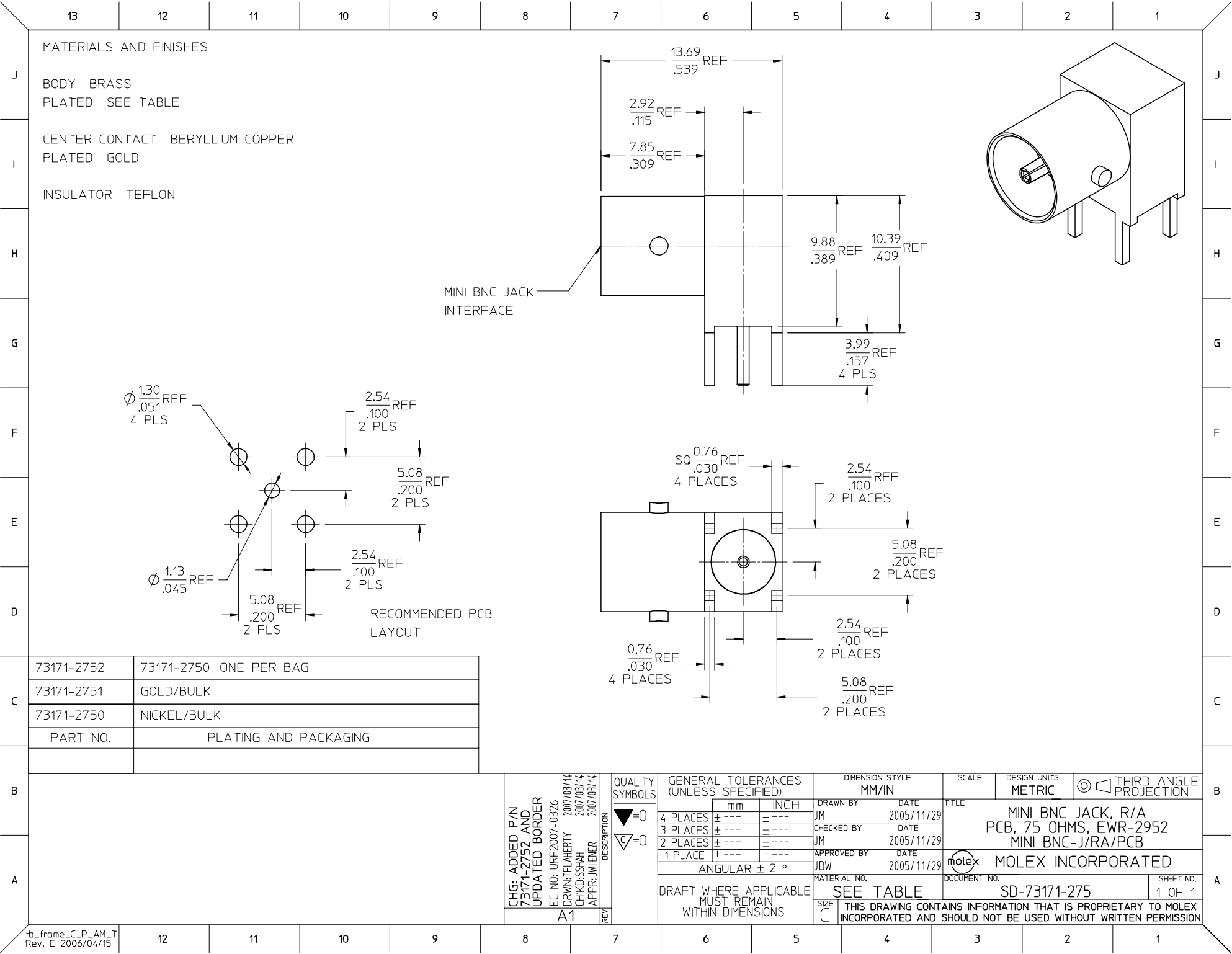




MATERIALS AND FINISHES

BODY BRASS
PLATED SEE TABLE

CENTER CONTACT BERYLLIUM COPPER
PLATED GOLD

INSULATOR TEFLON

MINI BNC JACK
INTERFACE

RECOMMENDED PCB
LAYOUT

73171-2752	73171-2750, ONE PER BAG
73171-2751	GOLD/BULK
73171-2750	NICKEL/BULK
PART NO.	PLATING AND PACKAGING

CHG: ADDED P/N 73171-2752 AND UPDATED BORDER EC NO: URF 2007-0326 2007/03/14 DRAWN: TELAHARTY 2007/03/14 CHKD: SHAH 2007/03/14 APPR: JIM ENER 2007/03/14	QUALITY SYMBOLS	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM/IN		SCALE	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION			
			 =0  =0		mm	INCH	DRAWN BY	DATE	TITLE MINI BNC JACK, R/A PCB, 75 OHMS, EWR-2952 MINI BNC-J/RA/PCB				
				4 PLACES	± .---	± .---	JM	2005/11/29					
				3 PLACES	± .---	± .---	CHECKED BY	DATE					
				2 PLACES	± .---	± .---	JM	2005/11/29					
				1 PLACE	± .---	± .---	APPROVED BY	DATE					
						ANGULAR ± 2 °						 MOLEX INCORPORATED	
						DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE			DOCUMENT NO. SD-73171-275		SHEET NO. 1 OF 1
							SIZE  C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					